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August 29, 2000

CAPACITOR BUILT-IN NON-CONTACT TYPE IC CARD AND ITS MANUFACTURE

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CORE TERMS: capacitor, card, resonance, antenna, coil, non-contact, substrate, branched,

linear

ENGLISH-ABST:

PROBLEM TO BE SOLVED: To provide a non-contact type IC card whose resonance circuit has a capacity-adjustable capacitor and to provide its manufacturing method.

SOLUTION: In this capacitor built-in non- contact type IC card provided with a resonance circuit consisting of an antenna coil 13 and a planar capacitor 15 in a card substrate wherein the capacitor capacity in the resonance circuit is adjustable, the capacitor has a configuration composed of branched linear pattern groups and the capacitor capacity can be adjusted by disconnecting a linear pattern from the branched part. The capacitor of such a non-contact type IC card can be manufactured by simultaneously forming a fine line capacitor pattern, the coil 13 and antenna coil connection terminals 141 and 142 on an antenna substrate 121A, covering the capacitor pattern with an insulating layer and further providing a

conductive plate.

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